

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3	board.ti. and kokufu.in.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/07/08 17:12
S2	6	("3644166" "4086095" "4967314" "5021296" "5481795" "6488869").PN.	USPAT; EPO; JPO	OR	ON	2005/07/08 17:14
S3	361	(conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 with (zinc zn nickel ni chromate silane) and (via hole) near2 through and laminat\$3	USPAT; EPO; JPO	OR	ON	2005/07/08 18:37
S4	135	"29"/\$ and (conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 with (zinc zn nickel ni chromate silane) and (via hole) near2 through and laminat\$3	USPAT; EPO; JPO	OR	ON	2005/07/08 18:44
S5	8	(conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 near3 agent with (zinc zn nickel ni chromate silane) and (via hole) near2 through and laminat\$3	USPAT; EPO; JPO	OR	ON	2005/07/08 18:50
S6	23	(copper conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 near3 (material agent) with (zinc zn nickel ni chromate silane) and (via hole) near2 through and circuit near3 board	USPAT; EPO; JPO	OR	ON	2005/09/12 17:49
S7	172	(wiring circuit\$3 copper conduct\$3 metal\$3) near2 (foil layer film) and (adhesive protect\$3 passivat\$3) near3 (material agent) with (zinc zn nickel ni chromate silane) and (via hole) near4 (substrate board)	USPAT; EPO; JPO	OR	ON	2005/09/12 17:51
S8	91	(wiring circuit\$3 copper conduct\$3 metal\$3) near2 (foil layer film) and (adhesive protect\$3 passivat\$3) near3 (material agent) with (zinc zn nickel ni chromate silane) and (via hole) near4 (substrate board) and (coat coating dispers\$3) and (pressing laminat\$3)	USPAT; EPO; JPO	OR	ON	2005/09/12 18:02
S9	0	(wiring circuit\$3 copper conduct\$3 metal\$3) near2 (foil layer film) and (adhesive protect\$3 passivat\$3) near3 (material agent) with (zinc zn nickel ni chromate silane) same (coat coating dispers\$3) and (via hole) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material)	USPAT; EPO; JPO	OR	ON	2005/09/12 18:04

S10	22	(wiring circuit\$3 copper conduct\$3 metal\$3) near3 (foil layer film) and (adhesive protect\$3 passivat\$3) with (zinc zn nickel ni chromate silane) same (coat coating dispers\$3) and (via hole) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material)	USPAT; EPO; JPO	OR	ON	2005/09/14 15:29
S11	25	(wiring circuit\$3 copper conduct\$3 metal\$3) near3 (foil layer film) with (coat coating dispers\$3) and (adhesive protect\$3 passivat\$3) with (zinc zn nickel ni chromate silane) and (via hole) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material)	USPAT; EPO; JPO	OR	ON	2005/09/12 18:09
S12	7	("5114543" "5346750" "5725706" "6014929" "6197407" "6359235" "6429114").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/12 18:11
S13	109	("5346750").URPN.	USPAT	OR	ON	2005/09/12 18:14
S14	9	("5780776" "5814883" "5901050" "6015722" "6025648" "6183592" "6222265" "6248959" "6265772").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/12 18:25
S15	7	("5346750" "5480503" "5481795" "5484647" "5498467" "5576519" "5744758").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/12 18:26
S16	7	("20010032700" "20030045164" "5346750" "5851646" "6300576" "6523258" "6596406").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/12 18:31
S17	5	("5346750" "5484647" "5807626" "5888627" "6326694").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/12 18:32
S18	1	"6565954".pn.	USPAT; EPO; JPO	OR	ON	2005/09/12 18:39
S19	1	"6197407".pn.	USPAT; EPO; JPO	OR	ON	2005/09/12 18:39
S20	19	(wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3) same (adhesive protect\$3 passivat\$3) with (zinc zn nickel ni chromate silane) and (via hole opening) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material)	USPAT; EPO; JPO	OR	ON	2005/09/14 15:38

S21	34	(wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3 plating) with (zinc zn nickel ni chromate silane) and (via hole opening) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) and (adhesive protect\$3 passivat\$3) near3 (agent material)	USPAT; EPO; JPO	OR	ON	2005/09/14 15:39
S22	72	(wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3 plating) with (zinc zn nickel ni chromate silane) and (via hole opening) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) and (adhesive protect\$3 passivat\$3) near3 (agent material layer)	USPAT; EPO; JPO	OR	ON	2005/09/14 18:28
S23	3	("4619871" "6107003" "6212769"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/14 18:14
S24	13	("3471631" "4349862" "5292574" "5373110" "5375042" "5590461" "5726863" "5939789" "5977490" "6139777" "6217987" "6259037"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/14 18:23
S25	148	(wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3 plating) with (zinc zn nickel ni chromate silane) and (via hole opening) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material)	USPAT; EPO; JPO	OR	ON	2005/09/14 18:29
S26	76	S25 not S22	USPAT; EPO; JPO	OR	ON	2005/09/14 18:30